

Amendments to the Specification:

At page 1, immediately following the title, add the following paragraph:

--This is a continuation of copending application number 09/730,263, filed on December 5, 2000.--

Delete the paragraphs appearing from page 2, line 24 to page 5, line 16.

Amend the paragraph appearing at page 5, lines 24-30 as follows:

FIG. 1A is a top plan view of the printhead structure after the first step of an exemplary embodiment of a the printhead fabrication process, i.e. after the inkjet thin film structure has been formed on the silicon substrate. FIG. 1B is a cross-sectional view of the printhead structure of FIG. 1A after a further step of the fabrication process, the TMAH etch process, has been performed to create a slot break trench.

At page 6, amend the paragraph appearing at lines 27-31 as follows:

FIG. 6A diagrammatically depicts in a top view of a substrate of a further embodiment, wherein trenches serving as chip stop bars are not connected at the corners. FIG. 6B is a cross-sectional view taken along line 6B-6B of FIG. 6A.